

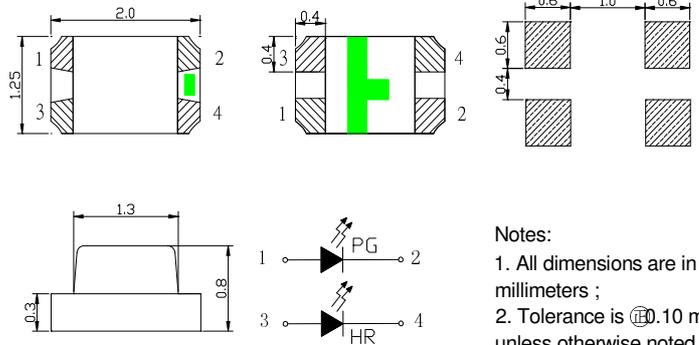
■Features

- Bi-Color
- Super high brightness of surface mount LED
- Water Clear Flat Mold
- Compact package outline
(LxWxT) of 2.0mm x 1.25mm x 0.8mm
- Compatible to IR reflow soldering.

■Applications

- Backlighting (switches, keys, etc.)
- Marker lights (e.g. steps, exit ways, etc.)

■Outline Dimension



Notes:
1. All dimensions are in millimeters ;
2. Tolerance is ± 0.10 mm unless otherwise noted.

■Absolute Maximum Rating

(Ta=25°C)

Item	Symbol	Value		Unit
		Red	PG	
DC Forward Current	I _F	30	30	mA
Pulse Forward Current*	I _{FP}	100	100	mA
Reverse Voltage	V _R	5	5	V
Power Dissipation	P _D	78	108	mW
Operating Temperature	T _{opr}	-40 ~ +85		°C
Storage Temperature	T _{stg}	-40 ~ +85		°C
Lead Soldering Temperature	T _{sol}	260°C/10sec		-

*Pulse width Max 0.1ms, Duty ratio max 1/10

■Electrical -Optical Characteristics

(Ta=25°C)

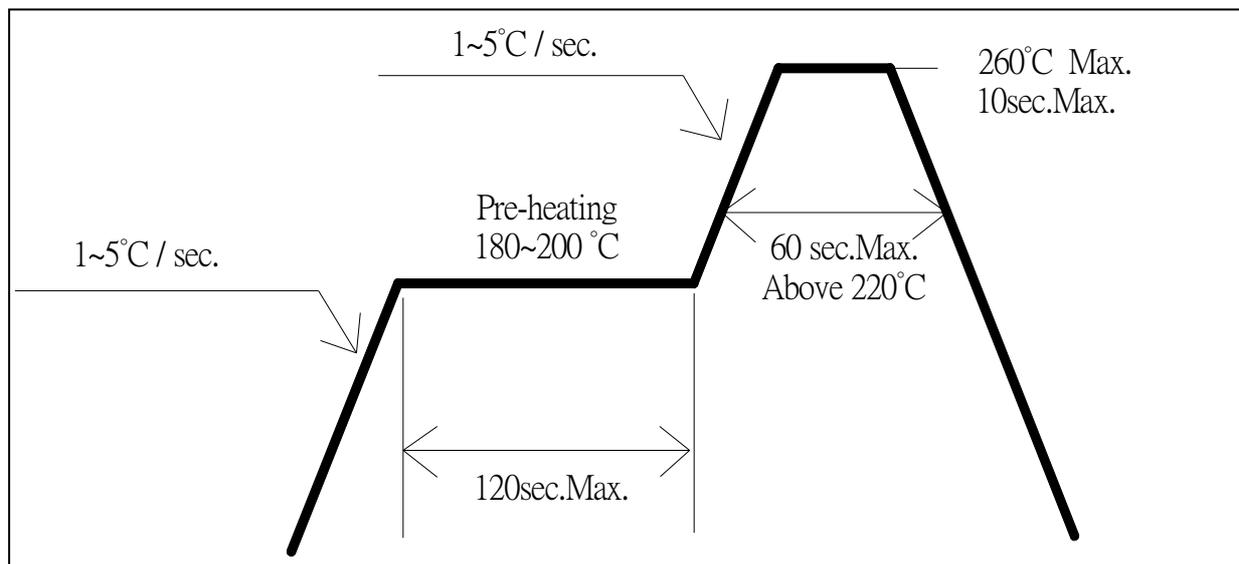
Part Number	Color			V _F (V)			I _R (μA)	I _v (mcd)			λD (nm)			2θ1/2(deg)
				Min.	Typ.	Max.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	Typ.
				I _F =20mA			V _R =5V	I _F =20mA						
OSRP0805C1E-0.8T	Red	R		1.8	2.1	2.6	10	80	150	-	617	625	630	120
	Pure Green	PG		2.8	3.1	3.6	10	300	450	-	517	525	530	120

*1 Tolerance of measurements of dominant wavelength is ± 1 nm
 *2 Tolerance of measurements of luminous intensity is $\pm 15\%$
 *3 Tolerance of measurements of forward voltage is ± 0.1 V

■ **Soldering Conditions**

Reflow Soldering		Hand Soldering	
Pre-Heat	180 ~ 200°C	Temperature Soldering time	350°C Max. 3 sec. Max. (one time only)
Pre-Heat Time	120 sec. Max.		
Peak temperature	260°C Max.		
Dipping Time	10 sec. Max.		
Condition	Refer to Temperature-profile		

• **Reflow Soldering Condition(Lead-free Solder)**



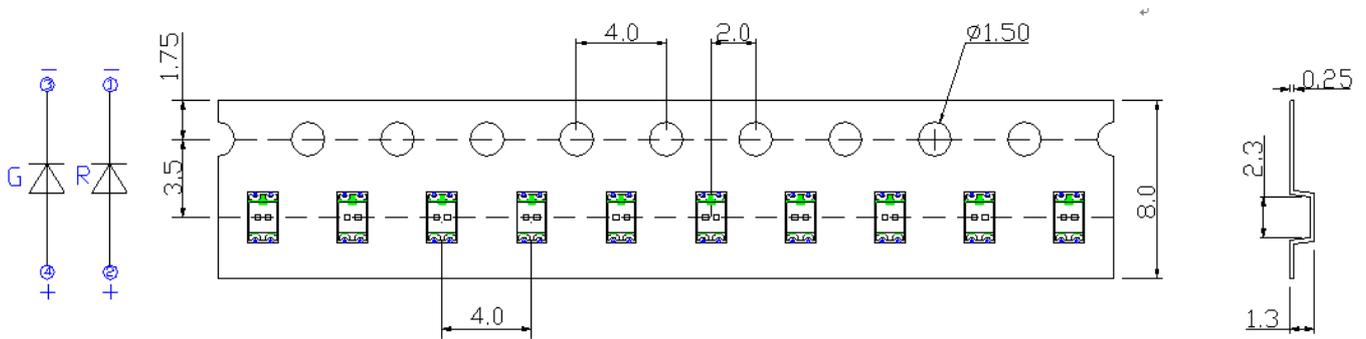
*Recommended soldering conditions vary according to the type of LED

*Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.

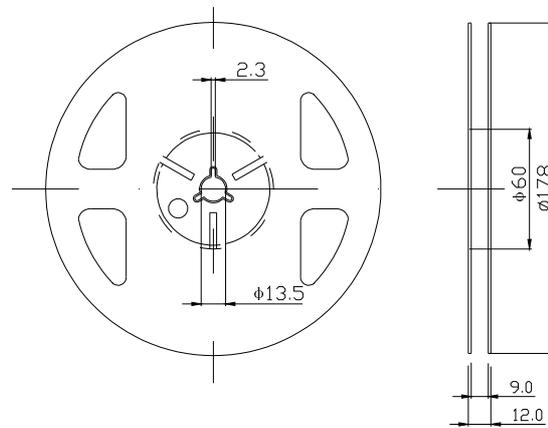
*A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.

- All SMD LED products are pb-free soldering available.
- Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

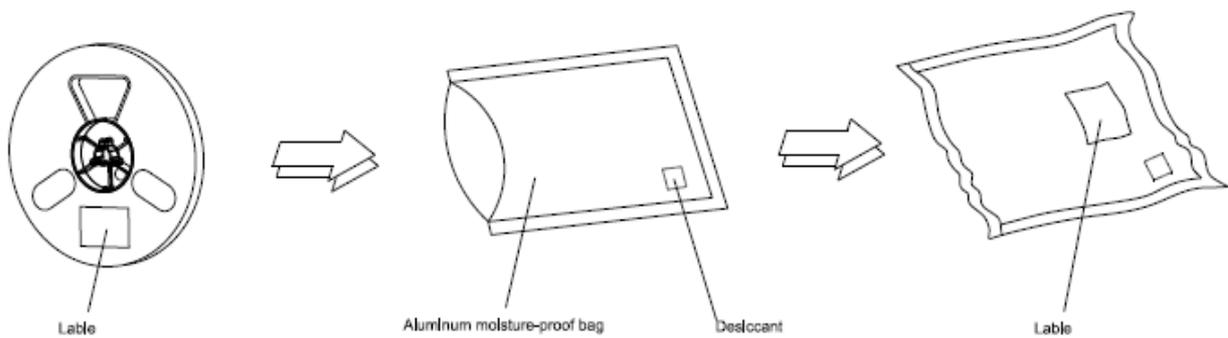
TAPING



■ **Reel Dimensions**



■ **Moisture Resistant Packaging**



Notes:

1. Unit: mm
2. 3000pcs/Reel